PCN Status:
Initial Notification

PCN Type:
Manufacturing Change

Microchip Parts Affected:
Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:
Qualification of Microchip Technology Tempe – Fab 2 as an additional fab site for selected LX3302A and LX34050 device families available in 14L TSSOP (4.4mm) package.

Pre and Post Change Summary:

	Pre Change	Post Change	
Fab Site	XFAB Silicon Foundries (Malaysia) (XFML)	XFAB Silicon Foundries (Malaysia) (XFML)	Microchip Technology Tempe – Fab 2 (TMGR)

Impacts to Data Sheet:
None

Change Impact
None

Reason for Change:
To improve manufacturability by qualifying Microchip Technology Tempe – Fab 2 (TGMR) as an additional fab location.

Change Implementation Status:
In Progress

Estimated Qualification Completion Date:
September 2023 (2339)

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	November 2022					>	September 2023				
Workweek	45	46	47	48	49		35	36	37	38	39
Initial PCN Issue				x							

Date
24-Nov-2022

PCN Type
Manufacturing Change

PCN
CAAN-22NDYJ154

Title
CCB 5398 Initial Notice: Qualification of Microchip Technology Tempe – Fab 2 as an additional fab site for selected LX3302A and LX34050 device families available in 14L TSSOP (4.4mm) package.

Product Category
Inductive Position Sensors

Affected CPNs

CAAN-22NDYJ154_Affected_CPN_11242022.pdf

CAAN-22NDYJ154_Affected_CPN_11242022.csv

Attachments

PCN_CAAN-22NDYJ154_Qual Plan.pdf

Home / Product Change Notifications / CAAN-22NDYJ154

Method to Identify Change:
Traceability code

Qualification Plan:
Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History:
November 24, 2022: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our PCN home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the PCN FAQ section.

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Affected Catalog Part Numbers (CPN)

LX3302AQPW-EASY
LX3302AQPW
LX3302AQPW-TR-EASY
LX3302AQPW-TR
LX34050QPW
LX34050QPW-VAO
LX34050QPW-TR
LX34050QPW-TR-VAO
LX3302AQPW-TR-C01

QUALIFICATION PLAN SUMMARY

PCN#: CAAN-22NDYJ154

Date:
November 17, 2022

Qualification of Microchip Technology Tempe – Fab 2 as an additional fab site for selected LX3302A and LX34050 device families available in 14L TSSOP (4.4mm) package.

Purpose: Qualification of Microchip Technology Tempe – Fab 2 as an additional fab site for selected LX3302A and LX34050 device families available in 14L TSSOP (4.4mm) package.

CCB: 5398

Test Name	Conditions	Sample Size	Qty of Lots	Total Units
Preconditioning	MSL-1/260°C	231	3	738
HAST	+130°C/85% RH for 96 hours or +110C/85%RH/264HRS	77	3	246
UHAST	+130°C/85% RH for 96 hours or +110C/85%RH/264HRS	77	3	246
Temp Cycle	-65°C to +150°C for 500 cycles or -55C to +150C for 1000cyc	77	3	246
HTSL	@175°C for 1008HRS	45	1	45
HTOL	@150°C for 1008HRS	77	3	246
EDR (endurance retention)	@150°C for 1008HRS	77	3	246
ELFR	@150°C for 48HRS	800	3	2400
ESD/HBM	Pre / Post ATE at Room, Hot; *include ±250V, ±500V, ±1kV, and ±2kV	12	1	12
ESD/CDM	Pre / Post ATE at Room, Hot; include ±250V, ±500V and ±750V on all pins	12	1	12
Latch Up	Pre / Post ATE at Room, Hot	12	1	12
Electrical Distributions	ATE at Room, Hot, Cold	30	3	90
LTDR (low temp data retention)	25°C , ATE Room, Hot	77	3	246